BATTERY PROTECTION IC FOR SINGLE-CELL PACK S-8201 Series

The S-8201 Series are lithium-ion/lithium polymer rechargeable battery protection ICs incorporating high-accuracy voltage detection circuit and delay circuit. The S-8201 Series are suitable for protection of single-cell lithium ion/lithium polymer battery packs from overcharge, overdischarge and overcurrent.

■ Features

(1) Internal high accuracy voltage detection circuit

Overcharge detection voltage
 3.9 V to 4.4 V (5 mV step),

Accuracy ± 25 mV (± 25 °C), ± 30 mV (± 5 °C to ± 55 °C)

Overcharge release voltage
 Overdischarge detection voltage
 Overdischarge release voltage
 Overdischarge release voltage
 Overcurrent 1 detection voltage
 Overcurrent 2 detection voltage
 Overcurrent 2 detection voltage
 Overcurrent 2 detection voltage
 Overcurrent 2 detection voltage
 Overcurrent 3.8 V to 4.4 V*1, Accuracy ±50 mV
 Overcurrent 1 detection voltage
 Overcurrent 2 detection voltage
 Overcurrent 2 detection voltage
 Overcurrent 3.8 V to 4.4 V*1, Accuracy ±50 mV
 Overcurrent 1 detection voltage
 Overcurrent 2 detection voltage
 Overcurrent 2 detection voltage

(2) High voltage device is used for charger connection pins. (VM pin and CO pin: Absolute maximum rating=28 V)

- (3) Delay times (Overcharge: t_{CU} , Overdischarge: t_{DL} , Overcurrent 1: t_{IOV1} , Overcurrent 2: t_{IOV2}) are generated by an internal circuit. (No external capacitor is necessary.)

 Accuracy $\pm 20\%$
- (4) The overcharge timer reset delay time (7 ms to 40 ms) is generated by an internal circuit only. (No external capacitor is necessary.)
- (5) Three-step overcurrent detection circuit is included. (Overcurrent 1, Overcurrent 2, Load short-circuiting)
- (6) Either charge function or charge inhibition function for 0 V battery can be selected.
- (7) Charger detection function and abnormal charge current detection function
 - The overdischarge hysteresis is released by detecting negative voltage at the VM pin (-0.7 V typ.). (Charger detection function)
 - When the output voltage of the DO pin is high and the voltage at the VM pin is equal to or lower than the charger detection voltage (-0.7 V typ.), the output voltage of the CO pin goes low. (Abnormal charge current detection function)
- (8) Low current consumption

• Operation 3.5 μA typ., 7.0 μA max.

• Power-down 0.1 μA max.

(9) Wide operating temperature range −40 °C to +85°C

(10) Small package 6-Pin SOT-23-6, 6-Pin SNB(B)

- *1. The overcharge hysteresis voltage is 0.0 V or can be selected from the range 0.1 V to 0.4 V in 50 mV step.
- Overcharge hysterests voltage (V_{HC})=Overcharge detection voltage-Overcharge release voltage
- *2. The overdischarge hysteresis voltage is 0.0 V or can be selected from the range 0.1 V to 0.7 V in 100 mV step.

Overdischarge hysteresis voltage (V_{HD})=Overdischarge release voltage-Overdischarge detection voltage

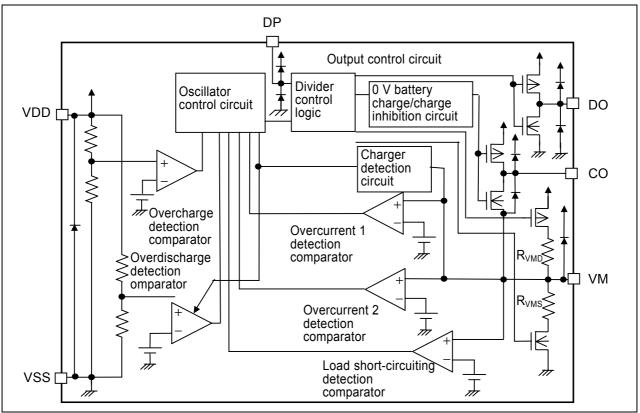
Applications

- Lithium-ion rechargeable battery packs
- Lithium polymer rechargeable battery packs

■ Packages

Package name	Drawing code						
	Package	Tape	Reel				
SOT-23-6	MP006-A	MP006-A	MP006-A				
6-Pin SNB(B)	BD006-A	BD006-A	BD006-A				

■ Block Diagram

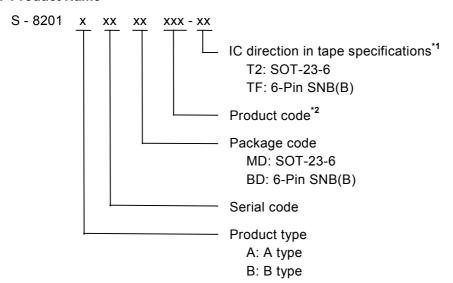


Remark The diodes in the figure are all parasitic diodes.

Figure 1

■ Product Name Structure

1. Product Name



- ***1.** Refer to the taping specifications at the end of this book.
- *2. Refer to the "Table 1 to 2" in the "2. Product Name List".

2. Product Name List

2-1. A type

Table 1 (1/2)

	Overdischarge	Overcharge	Overdischarge	Overdischarge	Overcurrent 1	0 V battery
Model No./Item	detection	release	detection	release	detection	charge
	voltage	voltage	voltage	voltage	voltage	function
S-8201AAABD-M5A-TF	4.3 V	4.1 V	2.3 V	2.3 V	0.13 V	Available
S-8201AABBD-M5B-TF	4.305 V	4.005 V	2.3 V	2.9 V	0.1 V	Available
S-8201AACBD-M5C-TF	4.295 V	3.995 V	2.3 V	2.9 V	0.1 V	Available
S-8201AADBD-M5D-TF	4.325 V	4.075 V	2.5 V	2.9 V	0.15 V	Unavailable
S-8201AAEBD-M5E-TF	4.350 V	4.150 V	2.3 V	3.0 V	0.20 V	Unavailable
S-8201AAFBD-M5F-TF	4.350 V	4.150 V	2.3 V	3.0 V	0.20 V	Available

Table 1 (2/2)

Model No./Item	Overcharge detection delay time	Overdischarge detection delay time	Overcurrent 1 detection delay time
S-8201AAABD-M5A-TF	4.6 s	150 ms	9 ms
S-8201AABBD-M5B-TF	4.6 s	150 ms	9 ms
S-8201AACBD-M5C-TF	4.6 s	150 ms	9 ms
S-8201AADBD-M5D-TF	1.2 s	150 ms	9 ms
S-8201AAEBD-M5E-TF	1.2 s	150 ms	9 ms
S-8201AAFBD-M5F-TF	1.2 s	150 ms	9 ms

Remark It is possible to change the detection voltages of the product other than above. The delay times can also be changed within the range-listed bellow. For details, contact SII marketing department.

Table 2

Delay time	Symbol	Selection range			Remarks
Overcharge detection delay time	t _{CU}	0.15 s	1.2 s	4.6 s	Choose from the left
Overdischarge detection delay time	t _{DL}	37.5 ms	150 ms	300 ms	Choose from the left
Overcurrent 1 detection delay time	t _{IOV1}	4.5 ms	9m s	18 ms	Choose from the left

Remark Values surrounded by bold lines are used in standard products.

2-2. B type

Table 3 (1/2)

	Overdischarge	Overcharge	Overdischarge	Overdischarge	Overcurrent 1	0 V battery
Model No./Item	detection	release	detection	release	detection	charge
	voltage	voltage	voltage	voltage	voltage	function
S-8201BAABD-M7A-TF	4.3 V	4.1 V	2.3 V	2.3 V	0.13 V	Available

Table 3 (2/2)

Model No./Item	Overcharge detection	Overdischarge detection	Overdischarge release	Overcurrent 1 detection
Model No./Item	delay time	delay time	delay time	delay time
S-8201BAABD-M7A-TF	4.6 s	150 ms	1.18 ms	9 ms

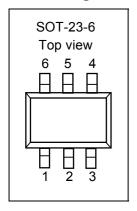
Remark It is possible to change the detection voltages of the product other than above. The delay times can also be changed within the range-listed bellow. For details, contact SII marketing department.

Table 4

Delay time	Symbol	Selection range			Remarks
Overcharge detection delay time	t _{CU}	0.15 s	1.2 s	4.6 s	Choose from the left
Overdischarge detection delay time	t _{DL}	37.5 ms	150 ms	300 ms	Choose from the left
Overcurrent 1 detection delay time	t _{IOV1}	4.5 ms	9m s	18 ms	Choose from the left

Remark Values surrounded by bold lines are used in standard products.

■ Pin Configurations



Pin No.	Pin name	Pin description
1	DO	FET gate control pin for discharge
		(CMOS output)
2	VM	Voltage detection pin between VM pin and VSS pin
		(Overcurrent detection pin)
3	CO	FET gate control pin for charge
		(CMOS output)
4	DP	Test pin for delay time acceleration
5	VDD	Positive power input pin
6	VSS	Negative power input pin

Table 5

Figure 2

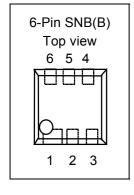


Table 6

Pin No.	Pin name	Pin description
1	CO	FET gate control pin for charge
		(CMOS output)
2	VM	Voltage detection pin between VM pin and VSS pin
		(Overcurrent detection pin)
3	DO	FET gate control pin for discharge
		(CMOS output)
4	VSS	Negative power input pin
5	DP	Test pin for delay time acceleration
6	VDD	Positive power input pin

Figure 3

■ Absolute Maximum Ratings

Table 7

(Ta=25 °C unless otherwise specified)

Item		Symbol	Applied pin	Absolute maximum ratings	Unit
Input voltage		V_{DS}	Between VDD and VSS	V_{SS} -0.3 to V_{SS} +12*1	V
		V_{DP}	DP	V_{SS} –0.3 to V_{DD} +0.3	
		V_{VM}	VM	V_{DD} –28 to V_{DD} +0.3	
Output voltage		V_{CO}	CO	V_{VM} =0.3 to V_{DD} +0.3	
			DO	V_{SS} –0.3 to V_{DD} +0.3	
Power dissipation	SOT-23-6	P_{D}	_	250	mW
	6-Pin SNB(B)			90	
Operating ambient temperature		Topr	_	−40 to +85	°C
Storage temperature	e	Tstg	_	−55 to +125	

^{*1.} Do not apply pulse-like noise of μ s order exceeding the above input voltage (V_{SS}+12 V). The noise causes damage to the IC.

Caution The absolute maximum ratings are rated values exceeding which the product could suffer physical damage. These values must therefore not be exceeded under any conditions.

■ Electrical Characteristics

1. Except Detection Delay Time (Ta=25°C)

Table 8

(Ta=25 °C unless otherwise specified)

(Ta=25 °C unless otherwise spec								
Item	Symbol	Condition	Remark	Min.	Тур.	Max.	Unit	Test circuit
[Detection Voltage, Release Vol	tage]							
Overcharge detection voltage,	V_{CU}	1		V _{CU} -0.025	V_{CU}	V _{CU} +0.025	V	1
V _{CU} =3.9 to 4.4 V, 5 mV Step			Ta= -5 °C to 55 °C ^{*1}	V _{CU} -0.03	V_{CU}	V _{CU} +0.03		
Overcharge release voltage, V _{CL} =3.8 to 4.4 V	V _{CL}	1	_	V _{CL} -0.05	V_{CL}	V _{CL} +0.05		
Overdischarge detection voltage, V _{DL} =2.0 to 3.0 V, 10 mV Step	V _{DL}	2	_	V _{DL} -0.05	V_{DL}	V _{DL} +0.05		2
Overdischarge release voltage, V _{DU} =2.0 to 3.4 V,	V _{DU}	2	_	V _{DU} 0.1	V_{DU}	V _{DU} +0.1		
Overcurrent detection voltage 1, V _{IOV1} =0.05 to 0.3 V, 10 mV Step	V _{IOV1}	3	_	V _{IOV1} 0.015	V_{IOV1}	V _{IOV1} +0.015		
Overcurrent detection voltage 2	V_{IOV2}	3	_	0.4	0.5	0.6		
Load short-circuiting detection voltage	V _{SHORT}	3	_	0.9	1.2	1.5		
Charger detection voltage	V_{CHA}	4	_	-1.0	-0.7	-0.4		
[Operation Voltage]		•				'		•
Operation voltage between VDD pin and VSS pin	V _{DSOP1}	_	Internal circuit operating voltage	1.5	_	8	V	_
Operation voltage between VDD pin and VM pin	V _{DSOP2}	_	Internal circuit operating voltage	1.5	_	28		
[Current Consumption]	•	•						
Current consumption in normal operation	I _{OPE}	5	V _{DD} =3.5 V, V _{VM} =0 V	1.0	3.5	7.0	μΑ	2
Current consumption at power down	I _{PDN}	5	V _{DD} =V _{VM} =1.5 V	_	_	0.1		
[Output Resistance]	•	•						•
CO pin High resistance	R _{COH}	7	V _{CO} =3.0 V, V _{DD} =3.5 V, V _{VM} =0 V	2.5	5	10	kΩ	4
CO pin Low resistance	R _{COL}	7	V _{CO} =0.5 V, V _{DD} =4.5 V, V _{VM} =0 V	2.5	5	10		
DO pin High resistance	R _{DOH}	8	V _{DO} =3.0 V, V _{DD} =3.5 V, V _{VM} =0 V	2.5	5	10		
DO pin Low resistance	R _{DOL}	8	V_{DO} =0.5 V, V_{DD} = V_{VM} =1.8 V	2.5	5	10		
[VM Internal Resistance]								
Internal resistance between VM pin and VDD pin	R _{VMD}	6	V _{DD} =1.8 V, V _{VM} =0 V	100	300	900	kΩ	3
Internal resistance between VM pin and VSS pin	R _{VMS}	6	V _{DD} =3.5 V, V _{VM} =1.0 V	10	20	40		
[0 V Battery Charging Function]		•	-	·				•
0 V battery charge starting charger voltage	V _{0CHA}	11	0 V battery charging available	1.2	_	_	V	2
0 V battery charge inhibition battery voltage	V _{0INH}	12	0 V battery charging unavailable	_	_	0.5		

^{*1} Since products are not screened at low and high temperature, the specification for this temperature range is guaranteed by design, not tested in production.

2. Except Detection Delay Time (Ta= -40 to 85 °C $^{^{\star1}}$)

Table 9

(Ta= -40 to 85 °C unless otherwise specified)

			(1a = -40 to	85 °C un	ess otherwi	se spe	ecifiea)
Item	Symbol	Condition	Remark	Min.	Тур.	Max.	Unit	Test circuit
[Detection voltage, Release Vol	tage]							•
Overcharge detection voltage, V _{CU} =3.9 to 4.4 V, 5 mV Step	V _{CU}	1	_	V _{CU} -0.055	V_{CU}	V _{CU} +0.040	V	1
Overcharge release voltage, V _{CL} =3.8 to 4.4 V	V _{CL}	1	_	V _{CL} -0.08	V _{CL}	V _{CL} +0.065	•	
Overdischarge detection voltage, V _{DL} =2.0 to 3.0 V, 10 mV Step	V _{DL}	2	_	V _{DL} -0.08	V_{DL}	V _{DL} +0.08	•	2
Overdischarge release voltage, V _{DU} =2.0 to 3.4 V	V _{DU}	2	_	V _{DU} -0.13	V_{DU}	V _{DU} +0.13	•	
Overcurrent 1 detection voltage, V _{IOV1} =0.05 to 0.3 V, 10 mV Step	V _{IOV1}	3	_	V _{IOV1} -0.021	V _{IOV1}	V _{IOV1} +0.021	•	
Overcurrent 2 detection voltage	V_{IOV2}	3	_	0.37	0.5	0.63	•	
Load short-circuiting detection voltage	V_{SHORT}	3	_	0.7	1.2	1.7	•	
Charger detection voltage	V_{CHA}	4	_	-1.2	-0.7	-0.2	•	
[Operation voltage]		•				•		
Operation voltage between VDD pin and VSS pin	V _{DSOP1}	_	Internal circuit operating voltage	1.5	_	8	V	_
Operation voltage between VDD pin and VM pin	V _{DSOP2}	_	Internal circuit operating voltage	1.5	_	28		
[Current consumption]								
Current consumption in normal operation	I _{OPE}	5	$V_{DD}=3.5 \text{ V}, V_{VM}=0 \text{ V}$	0.7	3.5	8.0	μΑ	2
Current consumption at power down	I _{PDN}	5	V _{DD} =V _{VM} =1.5 V	_	_	0.1		
[Output Resistance]								
CO pin High resistance	R _{COH}	7	V_{CO} =3.0 V, V_{DD} =3.5 V, V_{VM} =0 V	1.2	5	15	kΩ	4
CO pin Low resistance	R _{COL}	7	V _{CO} =0.5 V, V _{DD} =4.5 V, V _{VM} =0 V	1.2	5	15		
DO pin High resistance	R _{DOH}	8	V _{DO} =3.0 V, V _{DD} =3.5 V, V _{VM} =0 V	1.2	5	15		
DO pin Low resistance	R _{DOL}	8	$V_{DO}=0.5 \text{ V},$ $V_{DD}=V_{VM}=1.8 \text{ V}$	1.2	5	15	•	
[VM Internal Resistance]								•
Internal resistance between VM pin and VDD pin	R _{VMD}	6	V _{DD} =1.8 V, V _{VM} =0 V	78	300	1310	kΩ	3
Internal resistance between VM pin and VSS pin	R _{VMS}	6	V _{DD} =3.5V, V _{VM} =1.0 V	7.2	20	44		
[0 V Battery Charging Function]								
0 V battery charge starting charger voltage	V _{ocha}	11	0 V battery charging available	1.7		_	V	2
0 V battery charge inhibition battery voltage	V _{0INH}	12	0 V battery charging unavailable	_	_	0.3	•	

^{*1.} Since products are not screened at low and high temperature, the specification for this temperature range is guaranteed by design, not tested in production.

3. Detection Delay Time

3-1. S-8201AAA, S-8201AAB, S-8201AAC

Table 10

Item		Condition	Remark	Min.	Тур.	Max.	Unit	Test circuit
[Delay Time] 25 °C								
Overcharge detection delay time	t _{cu}	9	_	3.7	4.6	5.5	S	5
Overdischarge detection delay time	t_{DL}	9	_	120	150	180	ms	
Overcurrent 1 detection delay time	t _{IOV1}	10	_	7.2	9	11		
Overcurrent 2 detection delay time	t _{IOV2}	10	_	3.6	4.5	5.4		
Load short-circuiting detection delay time	t _{SHORT}	10	_	450	600	720	μs	
Overcharge timer reset delay time	ttr	13	_	10	18	28	ms	
[Delay Time] –40 to 85 °C*1								
Overcharge detection delay time	t _{cu}	9	_	2.5	4.6	7.8	s	5
Overdischarge detection delay time	t_{DL}	9	_	83	150	255	ms	
Overcurrent 1 detection delay time	t _{IOV1}	10	_	5	9	15		
Overcurrent 2 detection delay time	t _{IOV2}	10	_	2.5	4.5	7.7		
Load short-circuiting detection delay time	t _{SHORT}	10	_	310	600	1020	μs	
Overcharge timer reset delay time	ttr	13		7	18	40	ms	

^{*1.} Since products are not screened at low and high temperature, the specification for this temperature range is guaranteed by design.

3-2. S-8201AAD, S-8201AAE, S-8201AAF

Table 11

Item		Condition	Remark	Min.	Тур.	Max.	Unit	Test circuit
[Delay Time] 25 °C								
Overcharge detection delay time	t _{cu}	9	_	0.96	1.2	1.4	s	5
Overdischarge detection delay time	t_{DL}	9	_	120	150	180	ms	
Overcurrent 1 detection delay time	t _{IOV1}	10	_	7.2	9	11		
Overcurrent 2 detection delay time	t _{IOV2}	10	_	1.8	2.24	2.7		
Load short-circuiting detection delay time	t _{SHORT}	10	_	220	320	380	μs	
Overcharge timer reset delay time	ttr	13	_	10	18	28	ms	
[Delay Time] -40 to 85 °C*1								
Overcharge detection delay time	t _{CU}	9	_	0.7	1.2	2.0	s	5
Overdischarge detection delay time	t_{DL}	9	_	83	150	255	ms	
Overcurrent 1 detection delay time	t _{IOV1}	10	_	5	9	15		
Overcurrent 2 detection delay time	t _{IOV2}	10	_	1.2	2.24	3.8		
Load short-circuiting detection delay time	t _{SHORT}	10	_	150	320	540	μs	
Overcharge timer reset delay time	ttr	13	_	7	18	40	ms	

^{*1.} Since products are not screened at low and high temperature, the specification for this temperature range is guaranteed by design.

3-3. S-8201BAA

Table 12

Item	Symbol	Condition	Remark	Min.	Тур.	Max.	Unit	Test circuit
[Delay Time] 25 °C								
Overcharge detection delay time	t _{cu}	9	_	3.7	4.6	5.5	S	5
Overdischarge detection delay time	t_{DL}	9	_	120	150	180	ms	
Overdischarge release delay time	t _{DU}	9	_	0.94	1.18	1.42		
Overcurrent 1 detection delay time	t _{IOV1}	10	_	7.2	9	11		
Overcurrent 2 detection delay time	t _{IOV2}	10	_	3.6	4.5	5.4		
Load short-circuiting detection delay time	t _{SHORT}	10	_	450	600	720	μs	
Overcharge timer reset delay time	ttr	13	_	10	18	28	ms	
[Delay Time] –40 to 85 °C*1								
Overcharge detection delay time	t _{cu}	9	_	2.5	4.6	7.8	S	5
Overdischarge detection delay time	t_{DL}	9	_	83	150	255	ms	
Overdischarge release delay time	t _{DU}	9	_	0.65	1.18	2.01		
Overcurrent 1 detection delay time	t _{IOV1}	10	_	5	9	15		
Overcurrent 2 detection delay time	t _{IOV2}	10	_	2.5	4.5	7.7		
Load short-circuiting detection delay time	t _{SHORT}	10	_	310	600	1020	μs	
Overcharge timer reset delay time	ttr	13	_	7	18	40	ms	

^{*1.} Since products are not screened at low and high temperature, the specification for this temperature range is guaranteed by design.

■ Test Circuits

Caution Unless otherwise specified, the output voltage (V_{CO}) levels at CO pin and DO pin and "H" and "L" at the V_{DO} are judged by the threshold voltage (1.0 V) of the N channel FET. Judge the CO pin level with respect to V_{VM} and the DO pin level with respect to V_{SS} .

(1) Test Condition 1 (Test Circuit 1): Overcharge Detection Voltage, Overcharge Release Voltage

The overcharge detection voltage (V_{CU}) is defined as the voltage between VDD pin and VSS pin at which V_{CO} goes from "H" to "L" when the voltage V1 is gradually increased from the starting condition of V1=3.5 V. The overcharge release voltage (V_{CL}) is defined as the voltage between VDD pin and VSS pin at which V_{CO} goes from "L" to "H" when the voltage V1 is then gradually decreased. The overcharge hysteresis voltage (V_{HC}) is defined as the difference between the overcharge detection voltage (V_{CU}) and the overcharge release voltage (V_{CL}).

(2) Test Condition 2 (Test Circuit 2): Overdischarge Detection Voltage, Overdischarge Release Voltage

The overdischarge detection voltage (V_{DL}) is defined as the voltage between VDD pin and VSS pin at which V_{DO} goes from "H" to "L" when the voltage V1 is gradually decreased from the starting condition of V1=3.5 V, V2=0 V. The overdischarge release voltage (V_{DU}) is defined as the voltage between VDD pin and VSS pin at which V_{DO} goes from "L" to "H" when the voltage V1 is then gradually increased. The overdischarge hysteresis voltage (V_{HD}) is defined as the difference between the overcharge release voltage (V_{DU}) and the overdischarge detection voltage (V_{DL}).

(3) Test Condition 3 (Test Circuit 2): Overcurrent 1 Detection Voltage, Overcurrent 2 Detection Voltage, Load Short-circuiting Detection Voltage

The overcurrent 1 detection voltage is defined by the voltage between VM pin and VSS pin whose delay time for changing V_{DO} from "H" to "L" lies between the minimum and the maximum value of the overcurrent 1 detection delay time when the voltage V2 is increased rapidly within 10 μ s from the starting condition V1=3.5 V and V2=0 V.

The overcurrent 2 detection voltage is defined by the voltage between VM pin and VSS pin whose delay time for changing V_{DO} from "H" to "L" lies between the minimum and the maximum value of the overcurrent 2 detection delay time when the voltage V2 is increased rapidly within 10 μ s from the starting condition V1=3.5 V and V2=0 V.

The load short-circuiting detection voltage is defined by the voltage between VM pin and VSS pin whose delay time for changing V_{DO} from "H" to "L" lies between the minimum and the maximum value of the load short-circuiting detection delay time when the voltage V2 is increased rapidly within 10 μ s from the starting condition V1=3.5 V and V2=0 V.

(4) Test Condition 4 (Test Circuit 2): Charger Detection Voltage (=Abnormal Charge Current Detection Voltage)

Set V1=1.8 V and V2=0 V. Increase V1 gradually until V1= $V_{DL}+(V_{HD}/2)$, then decrease V2 from 0 V gradually. The voltage between VM pin and VSS pin when V_{DO} goes from "L" to "H" is the charger detection voltage (V_{CHA}). Charger detection voltage can be measured only in the product whose overdischarge hysteresis $V_{HD} \neq 0$.

Set V1=3.5 V and V2=0 V. Decrease V2 from 0 V gradually. The voltage between VM pin and VSS pin when V_{CO} goes from "H" to "L" is the abnormal charge current detection voltage. The abnormal charge current detection voltage has the same value as the charger detection voltage (V_{CHA}).

(5) Test Condition 5 (Test Circuit 2): Normal Operation Current Consumption, Power-down Current Consumption

Set V1=3.5 V and V2=0 V under normal condition. The current I_{DD} flowing through VDD pin is the normal operation consumption current (I_{OPE}).

Set V1=V2=1.5 V under overdischarge condition. The current I_{DD} flowing through VDD pin is the power-down current consumption (I_{PDN}).

(6) Test Condition 6 (Test Circuit 3): Internal Resistance between VM Pin and VDD Pin, Internal Resistance between VM Pin and VSS Pin

Set V1=1.8 V and V2=0 V. The resistance between VM pin and VDD pin is the internal resistance (R_{VMD}) between VM pin and VDD pin.

Set V1=3.5 V and V2=1.0 V. The resistance between VM pin and VSS pin is the internal resistance (R_{VMS}) between VM pin and VSS pin.

(7) Test Condition 7 (Test Circuit 4): CO Pin H Resistance, CO Pin L Resistance

Set V1=3.5 V, V2=0 V and V3=3.0 V. CO pin resistance is the CO pin H resistance (R_{COH}). Set V1=4.5 V, V2=0 V and V3=0.5 V. CO pin resistance is the CO pin L resistance (R_{COL}).

(8) Test Condition 8 (Test Circuit 4): DO Pin H Resistance, DO Pin L Resistance

Set V1=3.5 V, V2=0 V and V4=3.0 V. DO pin resistance is the DO pin H resistance (R_{DOH}). Set V1=1.8 V, V2=0 V and V4=0.5 V. DO pin resistance is the DO pin L resistance (R_{DOL}).

(9) Test Condition 9 (Test Circuit 5): Overcharge Detection Delay Time, Overdischarge Detection Delay Time, Overdischarge Release Delay Time

The overcharge detection delay time (t_{CU}) is the time needed for V_{CO} to change from "H" to "L" just after the V1 rapid increase within 10 μ s from the overcharge detection voltage (V_{CU}) –0.2 V to the overcharge detection voltage (V_{CU}) +0.2 V in the condition V2=0 V.

The overdischarge detection delay time (t_{DL}) is the time needed for V_{DO} to change from "H" to "L" just after the V1 rapid decrease within 10 μ s from the overdischarge detection voltage (V_{DL}) +0.2 V to the overdischarge detection voltage (V_{DL}) –0.2 V in the condition V2=0 V.

The overdischarge release delay time (t_{DU}) is the time needed for V_{DO} to change from "L" to "H" just after the V1 rapid increase within 10 μ s from the overdischarge release voltage (V_{DU}) –0.2 V to the overdischarge release voltage (V_{DU}) +0.2 V in the condition V2=0 V.

(10) Test Condition 10 (Test Circuit 5): Overcurrent 1 Detection Delay Time, Overcurrent 2 Detection Delay Time, Load Short-circuiting Detection Delay Time, Abnormal Charge Current Detection Delay Time

Set V1=3.5 V and V2=0 V. Increase V2 from 0 V to 0.35 V momentarily (within 10 μs). The time needed for V_{DO} to go "L" is overcurrent detection delay time 1 (t_{IOV1}).

Set V1=3.5 V and V2=0 V. Increase V2 from 0 V to 0.7 V momentarily (within 10 μ s). The time needed for V_{DO} to go "L" is overcurrent detection delay time 2 (t_{IOV2}).

Set V1=3.5 V and V2=0 V. Increase V2 from 0 V to 1.6 V momentarily (within 10 μ s). The time needed for V_{DO} to go "L" is the load short-circuiting detection delay time (t_{SHORT}).

Set V1=3.5 V and V2=0 V. Decrease V2 from 0 V to -1.1 V momentarily (within 10 μ s). The time needed for V_{CO} to go "L" is the abnormal charge current detection delay time. The abnormal charge current detection delay time has the same value as the overcharge detection delay time.

(11) Test Condition 11 (Test Circuit 2): 0 V Battery Charge Starting Charger Voltage (Product with 0 V Battery Charge Function)

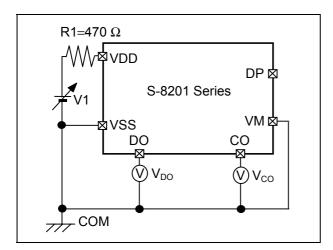
Set V1=V2=0 V and decrease V2 gradually. The voltage between VDD pin and VM pin when V_{CO} goes "H" (V_{VM} +0.1 V or higher) is the 0 V battery charge starting charger voltage (V_{0CHA}).

(12) Test Condition 12 (Test Circuit 2): 0 V Battery Charge Inhibition Battery Voltage (Product with 0 V Battery Charge Inhibition Function)

Set V1=0 V and V2= -4 V and Increase V1 gradually. The voltage between VDD pin and VSS pin when V_{CO} goes "H" (V_{VM} +0.1 V or higher) is the 0 V battery charge inhibition battery voltage (V_{OINH}).

(13) Test Condition 13 (Test Circuit 5): Overcharge Timer Reset Delay Time

Set V2=0 V. Increase V1 from overcharge detection voltage (V_{CU}) -0.2 V to overcharge detection voltage (V_{CU}) +0.2 V momentarily (within 10 μ s), then decrease V1 again to overcharge detection voltage (V_{CU}) -0.2 V momentarily (within 10 μ s) after half the overcharge detection delay time (t_{CU}) has elapsed. Following ttr Min., again increase V1 to overcharge detection voltage (V_{CU}) +0.2 V momentarily (within 10 μ s) and check that V_{CO} changes from "H" to "L" after the overcharge detection delay time from when V1 is first increased momentarily (within 10 μ s) to overcharge detection voltage (V_{CU}) +0.2 V. Set V2= 0V. Increase V1 from overcharge detection voltage (V_{CU}) -0.2 V momentarily (within 10 μ s), then decrease V1 again to overcharge detection voltage (V_{CU}) -0.2 V momentarily (within 10 μ s) after half the overcharge detection delay time (V_{CU}) has elapsed. Following ttr Max., again increase V1 to overcharge detection voltage (V_{CU}) +0.2 V momentarily (within 10 V_{CO}) and check that V_{CO} stays "H" after the overcharge detection delay time from when V1 is first increased momentarily (within 10 V_{CO}) to overcharge detection voltage (V_{CU}) +0.2 V.



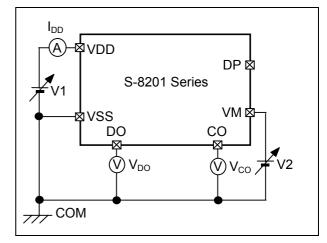


Figure 4 Test Circuit 1

S-8201 Series

V1

S-8201 Series

VM

DO

CO

A

I_{VM}

V2

Figure 5 Test Circuit 2

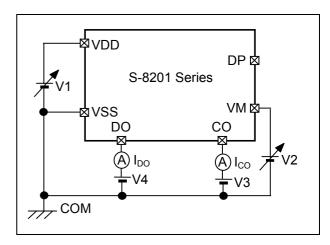


Figure 6 Test Circuit 3

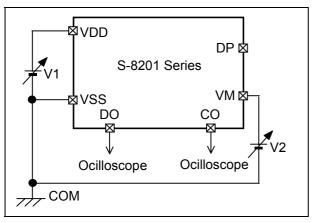


Figure 8 Test Circuit 5

Figure 7 Test Circuit 4

Operation

Remark Refer to the "■ Example for Battery Protection IC Connection".

1. Normal Condition

The S-8201 Series monitors the voltage of the battery connected between VDD pin and VSS pin and the voltage difference between VM pin and VSS pin to control charging and discharging. When the battery voltage is in the range from the overdischarge detection voltage (V_{DL}) to the overcharge detection voltage (V_{CU}), and the VM pin voltage is in the range from the charger detection voltage (V_{CHA}) to the overcurrent 1 detection voltage (V_{IOV1}), the IC turns both the charging and discharging control FETs on. This condition is called the normal condition, and in this condition charging and discharging can be carried out freely.

Caution When a battery is connected to the IC for the first time, the battery may not enter dischargeable state. In this case, set the VM pin voltage equal to the VSS pin voltage or connect a charger to enter the normal condition.

2. Overcurrent Condition (Overcurrent 1 Detection, Overcurrent 2 Detection, and Load Short-circuiting Detection)

When the condition in which VM pin voltage is equal to or higher than the overcurrent detection voltage, condition that caused by the excess of discharging current over a specified value, continues longer than the overcharge detection delay time in a battery under the normal condition, the S-8201 Series turns the discharging control FET off to stop discharging. This condition is called the overcurrent condition. Though the VM pin and VSS pin are shorted by the resistor in the IC (R_{VMS}) under the overcurrent condition provided that the VM pin voltage is pulled to the V_{DD} level by the load as long as the load is connected

The VM pin voltage returns to V_{SS} level when the load is released. The overcurrent condition returns to the normal condition when the impedance between the EB+ and EB- pin (Refer to **Figure 14**) becomes higher than the automatic recoverable impedance and the IC detects that the VM pin potential is lower than the overcurrent 1 detection voltage (V_{IOV1}).

Caution The automatic recoverable impedance changes depending on the battery voltage and overcurrent 1 detection voltage settings.

3. Overcharge Condition

When the battery voltage becomes higher than the overcharge detection voltage (V_{CU}) during charging under the normal condition and the detection continues for the overcharge detection delay time (t_{CU}) or longer, the S-8201 Series turns the charging control FET off to stop charging. This condition is called the overcharge condition.

The overcharge condition is released by the following two cases ((1) and (2)):

- (1) When the battery voltage falls below the overcharge release voltage, which is equal to the overcharge detection voltage (V_{CU})–overcharge detection hysteresis voltage (V_{HC}), the S-8201 Series turns the charging control FET on and turns to the normal condition.
- (2) When a load is connected and discharging starts, the S-8201 Series turns the charging control FET on and returns to the normal condition. Just after the load is connected and discharging starts, the discharging current flows through the parasitic diode in the charging control FET. At this moment the VM pin potential becomes V_f voltage, the voltage for the parasitic diode, higher than V_{SS} level. When the battery voltage goes under the overcharge detection voltage (V_{CU}) and provided that the VM pin voltage is higher than the overcurrent 1 detection voltage, the S-8201 Series releases the overcharge condition.
- Caution 1. If the battery is charged to a voltage higher than the overcharge detection voltage (V_{CU}) and the battery voltage does not fall below the overcharge detection voltage (V_{CU}) even when a heavy load is connected, the detection of overcurrent 1, overcurrent 2 and load short-circuiting does not work. Since an actual battery has the internal impedance of several dozens of m Ω , the battery voltage drops immediately after a heavy load which causes overcurrent is connected, and the detection of overcurrent 1, overcurrent 2 and load short-circuiting then works.
 - 2. When a charger is connected after the overcharge detection, the overcharge condition is not released even if the battery voltage is below the overcharge release voltage V_{CL} (=V_{CU}-V_{HC}). The overcharge condition is released when the VM pin voltage goes over the charger detection voltage (V_{CHA}) by removing the charger.
 - 3. If the overcharge release pulse for less than the overcharge timer reset delay time (ttr) is input during the overcharge detection delay time (t_{CU}) that after exceeding the overcharge detection voltage (V_{CU}), the t_{CU} keeps the count. However, if the overcharge release pulse is input for ttr or longer under the same conditions, the t_{CU} count is reset.

4. Overdischarge Condition

When the battery voltage falls below the overdischarge detection voltage (V_{DL}) during discharging under the normal condition and the detection continues for the overdischarge detection delay time (t_{DL}) or longer, the S-8201 Series turns the discharging control FET off to stop discharging. This condition is called the overdischarge condition. When the discharging control FET turns off, the VM pin voltage is pulled up by the resistor between VM pin and VDD pin in the IC (R_{VMD}). The voltage difference between VM pin and VDD pin then falls bellow 1.3 V (typ.), the current consumption is reduced to the power-down current consumption (I_{PDN}). This condition is called the power-down condition.

The power-down condition is released when a charger is connected and the voltage difference between VM pin and VDD pin becomes 1.3 V (typ.) or higher. Moreover when the battery voltage becomes the overdischarge detection voltage (V_{DL}) or higher the S-8201 Series turns the discharging FET on and returns to the normal condition.

5. Charger Detection

When a battery in the overdischarge condition is connected to a charger and provided that the VM pin voltage is lower than the charger detection voltage (V_{CHA}), the S-8201 Series releases the overdischarge condition and turns the discharging control FET on as the battery voltage becomes equal to or higher than the overdischarge detection voltage (V_{DL}) since the charger detection function works. This action is called charger detection.

When a battery in the overdischarge condition is connected to a charger and provided that the VM pin voltage is not lower than the charger detection voltage (V_{CHA}), the S-8201 Series releases the overdischarge condition when the battery voltage reaches the overdischarge detection voltage (V_{DL}) + overdischarge hysteresis (V_{HD}) or higher.

6. Abnormal Charge Current Detection

becomes less than charger detection voltage (V_{CHA}).

If the VM pin voltage falls below the charger detection voltage (V_{CHA}) during charging under normal condition and it continues for the overcharge detection delay time (t_{CU}) or longer, the charging control FET turns off and charging stops. This action is called the abnormal charge current detection. Abnormal charge current detection works when the DO pin voltage is "H" and the VM pin voltage falls below the charger detection voltage (V_{CHA}). Consequently, if an abnormal charge current flows to an over-discharged battery, the S-8201 Series turns the charging control FET off and stops charging after the battery voltage becomes higher than the overdischarge detection voltage which make the DO pin voltage "H", and still after the overcharge detection delay time (t_{CU}) elapses. Abnormal charge current detection is released when the voltage difference between VM pin and VSS pin

7. Delay Circuits

The detection delay times are generated by dividing the approximate 3.5 kHz clock with a counter.

Caution1. The detection delay time for overcurrent 2 and load and short-circuiting start when the overcurrent 1 is detected. As soon as the overcurrent 2 or load short-circuiting is detected over the detection delay time for overcurrent 2 or load short-circuiting after the detection of overcurrent 1, the S-8201 Series turns the discharging control FET off.

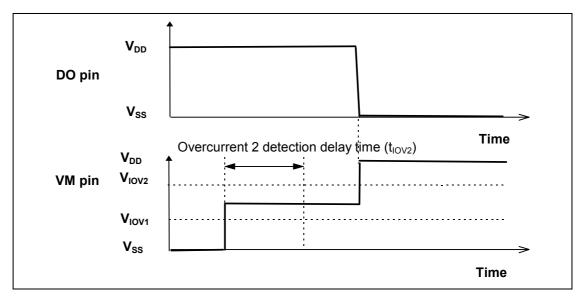


Figure 9

- When the overcurrent is detected and it continues for longer than the overdischarge detection delay time without releasing the load, the condition changes to the powerdown condition when the battery voltage falls below the overdischarge detection voltage.
- 3. When the battery voltage falls below the overdischarge detection voltage due to the overcurrent, the S-8201 Series turns the discharging control FET off by the overcurrent detection. And in this case the recovery of the battery voltage is so slow that the battery voltage after the overdischarge detection delay time is still lower than the overdischarge detection voltage, the S-8201 Series transits to the power-down condition.

8. DP Pin

The DP pin is a test pin for delay time acceleration. When the DP pin is set to the VDD pin potential, the delay time is reduced by about 1/15 to 1/40. (25°C). The DP pin should be left open during normal operation.

9. 0 V Battery Charge Function

This function is used to recharge the connected battery whose voltage is 0 V due to the self-discharge. When the 0V battery charge starting charger voltage (V_{0CHA}) or higher is applied between EB+ and EB- pins by connecting a charger, the charging control FET gate is fixed to VDD pin voltage. When the voltage between the gate and source of the charging control FET becomes equal to or higher than the turn-on voltage by the charger voltage, the charging control FET turns on to start charging. At this time, the discharging control FET is off and the charging current flows through the internal parasitic diode in the discharging control FET. When the battery voltage becomes equal to or higher than the overdischarge release voltage (V_{DU}), the S-8201 Series enters the normal condition.

- Caution 1. Some battery providers do not recommend charging for completely self-discharged battery. Please ask battery providers before determining the 0 V battery charge function.
 - 2. The 0 V battery charge function has higher priority than the abnormal charge current detection function. Consequently, a product with the 0 V battery charge function charges a battery forcedly and abnormal charge current cannot be detected when the battery voltage is low.

10. 0 V battery charge inhibition function

This function inhibits the recharging when a battery which is short-circuited (0 V) internally is connected. When the battery voltage is 0.6 V (typ.) or lower, the charging control FET gate is fixed to EB– pin voltage to inhibit charging. When the battery voltage is the 0 V battery charge inhibition battery voltage (V_{OINH}) or higher, charging can be performed.

Caution Some battery providers do not recommend charging for completely self-discharged battery. Please ask battery providers before determining the 0 V battery charge function.

■ Timing Chart

1. Overcharge and Overdischarge Detection

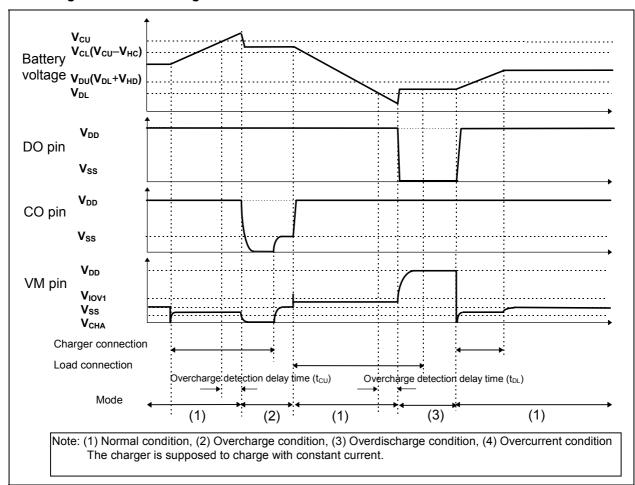


Figure 10

2. Overcurrent Detection

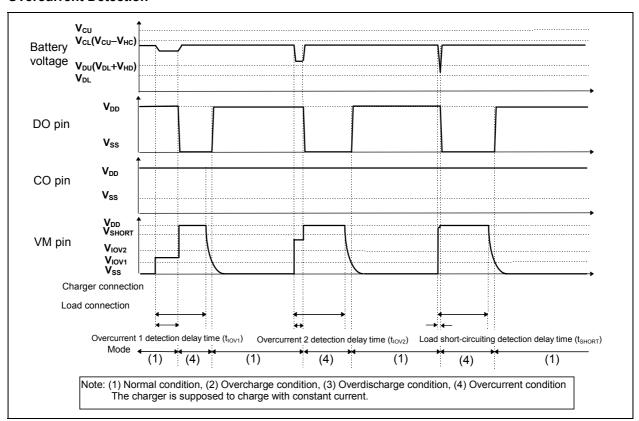


Figure 11

3. Charger Detection

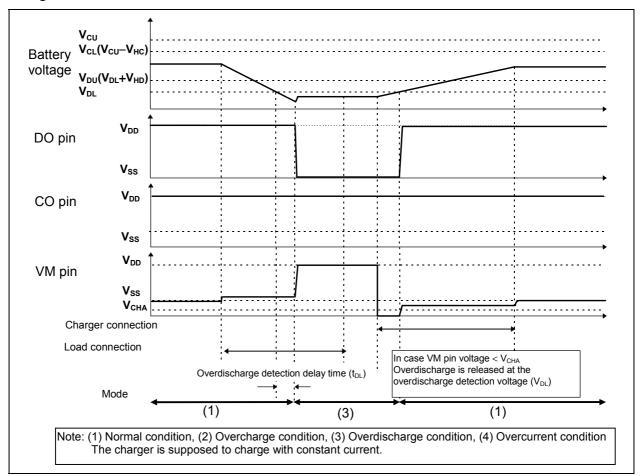


Figure 12

4. Abnormal Charge Current Detection

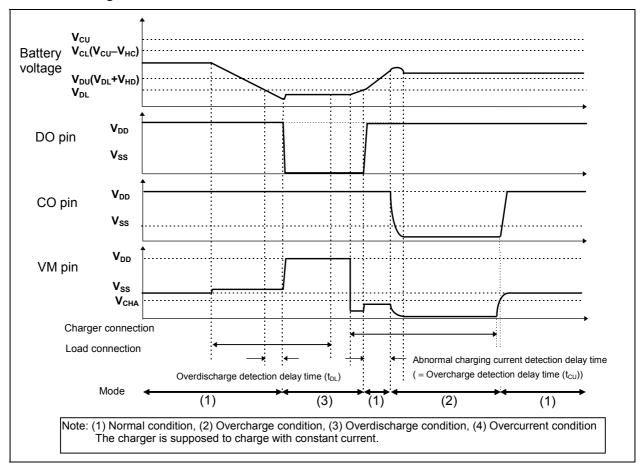


Figure 13

EB-

EB+ R1 470Ω **VDD** C₁ Battery | 0.1 μF S-8201Series Ø DP VSS DO CO VM R2 FET1 FET2 $2 k\Omega$

■ Example for Battery Protection IC Connection

Figure 14

Table 42	Constant for	Evtornal	Componente
Table 13	Constant for	External	Components

Symbol	Parts	Purpose	Recommend	Min.	Max.	Remarks
FET1	Nch MOS FET	Charge control	_		_	Threshold voltage≤overdischarge detection voltage ^{*1} , Gate to source withstand voltage≥Charger voltage
FET2	Nch MOS FET	Discharge control	_		_	Threshold voltage≤overdischarge detection voltage*1, Gate to source withstand voltage≥Charger voltage
R1	Resistor	ESD protection, For power fluctuation	470 Ω	300 Ω	1 kΩ	Resistance should be as small as possible to avoid lowering of the overcharge detection accuracy caused by VDD pin current.*2
C1	Capacitor	For power fluctuation	0.1 μF	0.022 μF	1.0 μF	Install a capacitor of 0.022 µF or higher between VDD pin and VSS pin.*3
R2	Resistor	Protection for reverse connection of a charger	2 kΩ	300 Ω	4 kΩ	Select a resistance as large as possible to prevent current when a charger is reversely connected.*4

- *1. If the threshold voltage of an EFT is low, the FET may not cut the charging current.
 - If an FET with a threshold voltage equal to or higher than the overdischarge detection voltage is used, discharging may be stopped before overdischarge is detected.
 - If the withstand voltage between the gate and source is lower than the charger voltage, the FET may destroy.
- *2. If R1 has a high resistance, the voltage between VDD pin and VSS pin may exceed the absolute maximum rating when a charger is connected reversely since the current flows from the charger to the IC. Insert a resistor of 300 Ω or higher as R1 for ESD protection.
- *3. If a capacitor of less than $0.022~\mu F$ is installed as C1, DO may oscillate when load short-circuiting is detected. Be sure to install a capacitor of $0.022~\mu F$ or higher as C1.
- *4. If R2 has a resistance higher than 4 $k\Omega$, the charging current may not be cut when a high-voltage charger is connected.

Caution 1. The DP pin should be open.

2. The above connection diagram and constants will not guarantees successful operation. Perform through evaluation using the actual application to set the constant.

■ Precautions

- The application condition for input voltage, output voltage and load current should not exceed the package power dissipation.
- Do not apply an electrostatic discharge to this IC that exceeds the performance ratings of the built-in electrostatic protection circuit.
- SII claims no responsibility for any and all disputes arising out of or in connection with any infringement of the products including this IC upon patents owned by a third party.

■ Typical Characteristics (Typical Data)

1. Detection/Release Voltage Temperature Characteristics

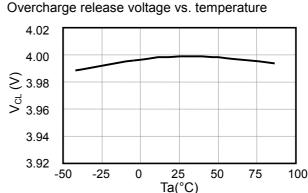
Overcharge detection voltage vs.temperature

4.44
4.42

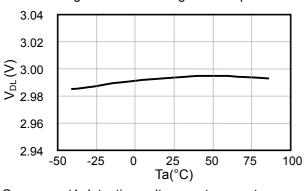
4.40

3
4.38
4.36
4.34
-50 -25 0 25 50 75 100

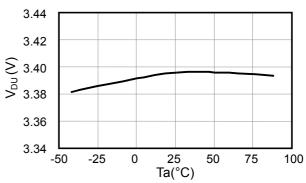
Ta(°C)



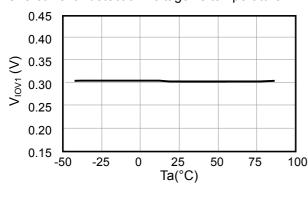
Overdischarge detection voltage vs. temperature



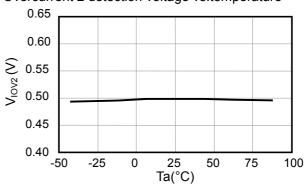
Overdischarge release voltage vs.temperature



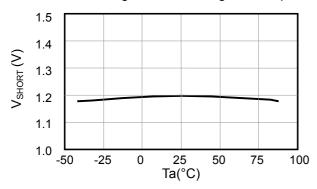
Overcurrent1 detection voltage vs.temperature



Overcurrent 2 detection voltage vs.temperature

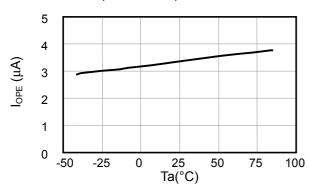


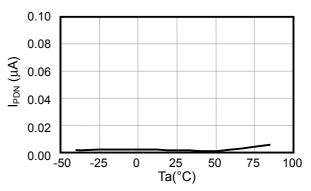
Load short-circuiting detection voltage vs. temperature



2. Current Consumption Temperature Characteristics

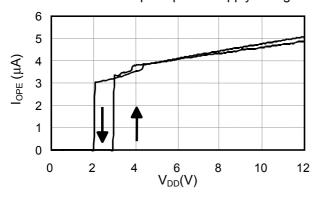
Current consumption vs.temperature in normal mode Current consumption vs.temperature in power-down mode





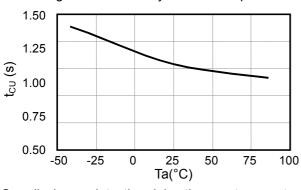
3. Current Consumption Power Voltage Characteristics (Ta=25°C)

Current consumption power supply voltage dependency

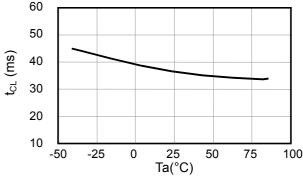


4. Detection/Release Delay Time Temperature Characteristics

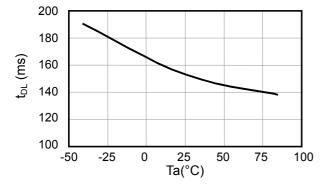
Overcharge detection delay time vs. temperature



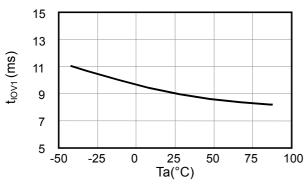
Overcharge release delay time vs. temperature

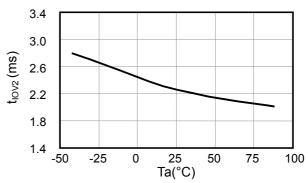


Overdischarge detection delay time vs. temperature

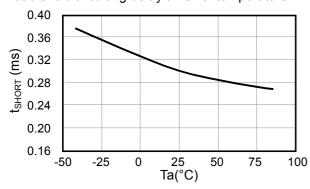


Overcurrent 1 detection delay time vs. temperature Overcurrent 2 detection delay time vs. temperature

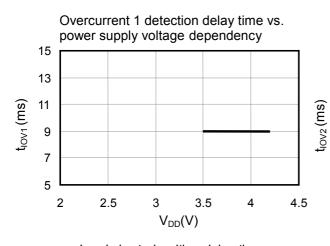


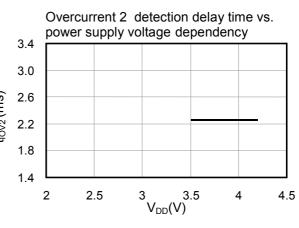


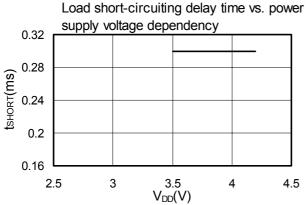
Load short-circuiting delay time vs. temperature



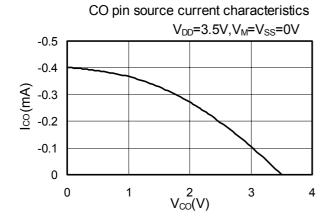
5. Delay Time Power-voltage Characteristics (Ta=25°C)

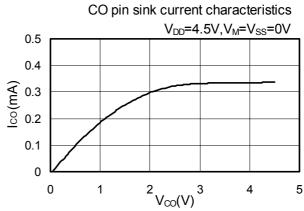


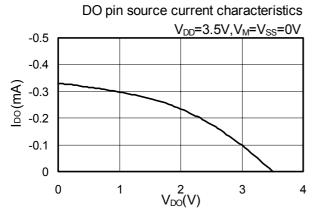


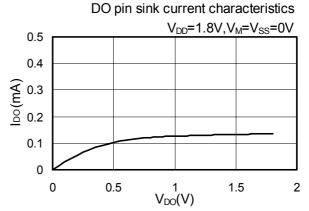


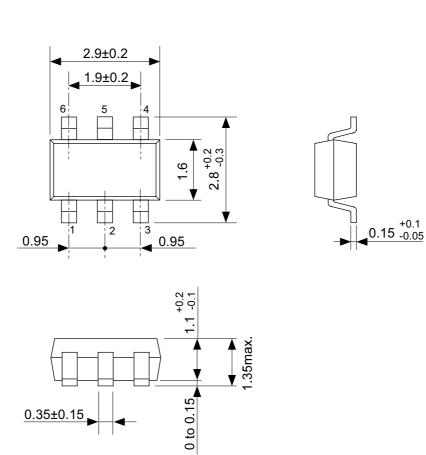
6. CO Pin/DO Pin Output Current Characteristics (Ta=25°C)







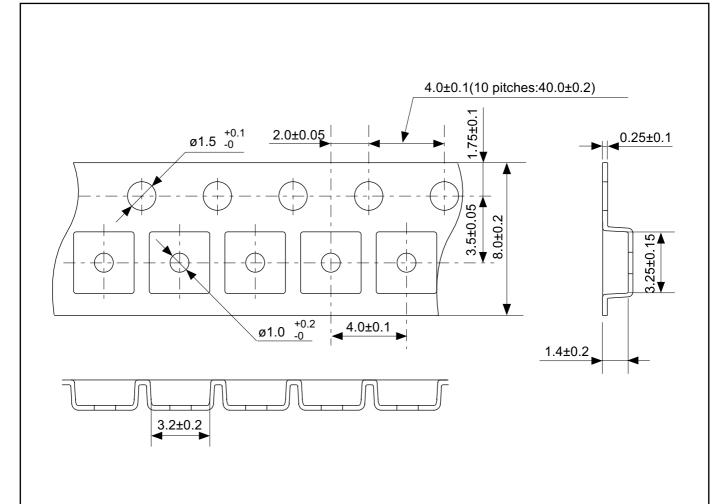


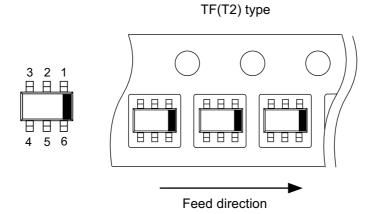


0.35±0.15

No. MP006-A-P-SD-1.1

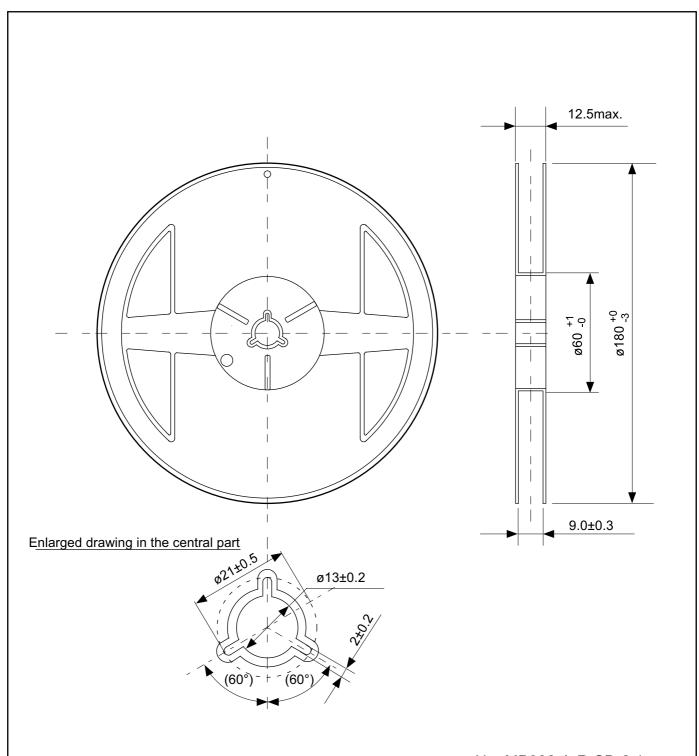
TITLE	SOT236-A-PKG Dimensions		
No.	MP006-A-P-SD-1.1		
SCALE			
UNIT	mm		
Seiko Instruments Inc.			





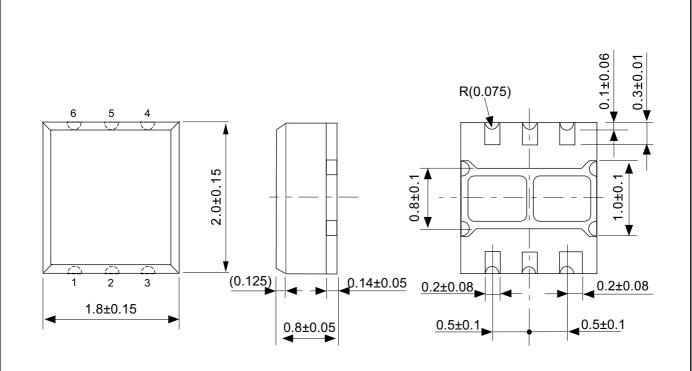
No. MP006-A-C-SD-3.1

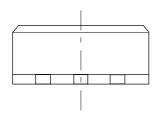
TITLE	SOT236-A-Carrier Tape					
No.	MP006-A-C-SD-3.1					
SCALE						
UNIT	mm					
Seiko Instruments Inc.						



No. MP006-A-R-SD-2.1

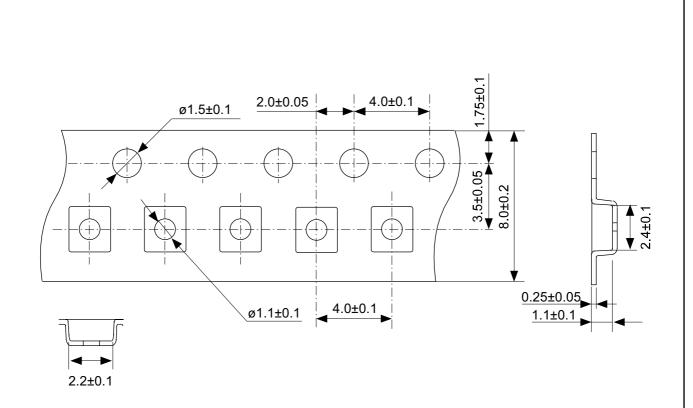
TITLE	SOT236-A-Reel				
No.	MP006	-A-R-SD-2	1		
SCALE		QTY	3,000		
UNIT	mm				
Seiko Instruments Inc.					
Selko ilistruments inc.					

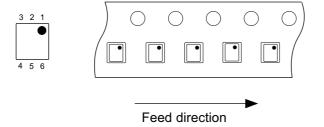




No. BD006-A-P-SD-1.1

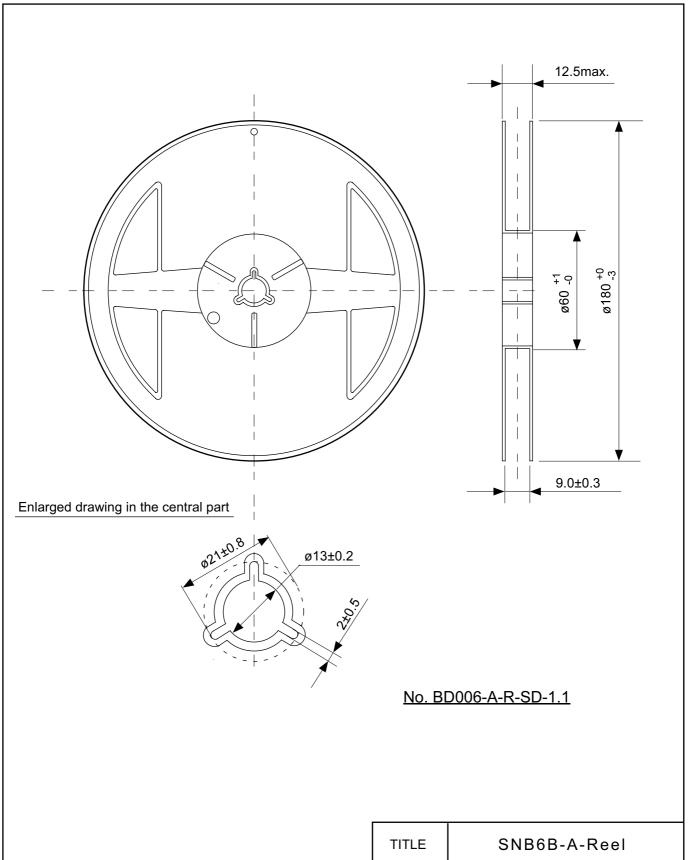
TITLE	SNB6B-A-PKG Dimensions		
No.	BD006-A-P-SD-1.1		
SCALE			
UNIT	mm		
Seiko Instruments Inc.			





No. BD006-A-C-SD-2.1

TITLE	SNB6B-A-Carrier Tape		
No.	BD006-A-C-SD-2.1		
SCALE			
UNIT	mm		
Seiko Instruments Inc.			



TITLE	SNB6B-A-Reel					
No.	BD00	BD006-A-R-SD-1.1				
SCALE		QTY.	3,000			
UNIT	mm	-	•			
Seiko Instruments Inc.						
Gerko matidilenta ilic.						

- The information described herein is subject to change without notice.
- Seiko Instruments Inc. is not responsible for any problems caused by circuits or diagrams described herein whose related industrial properties, patents, or other rights belong to third parties. The application circuit examples explain typical applications of the products, and do not guarantee the success of any specific mass-production design.
- When the products described herein are regulated products subject to the Wassenaar Arrangement or other agreements, they may not be exported without authorization from the appropriate governmental authority.
- Use of the information described herein for other purposes and/or reproduction or copying without the express permission of Seiko Instruments Inc. is strictly prohibited.
- The products described herein cannot be used as part of any device or equipment affecting the human body, such as exercise equipment, medical equipment, security systems, gas equipment, or any apparatus installed in airplanes and other vehicles, without prior written permission of Seiko Instruments Inc.
- Although Seiko Instruments Inc. exerts the greatest possible effort to ensure high quality and reliability, the failure or malfunction of semiconductor products may occur. The user of these products should therefore give thorough consideration to safety design, including redundancy, fire-prevention measures, and malfunction prevention, to prevent any accidents, fires, or community damage that may ensue.